

# Jason Asariah

Irvine, CA | (951) 594-1013 | [JasonAsariah.com](https://www.linkedin.com/in/JasonAsariah) | [JasonSean.Asariah@calbaptist.edu](mailto:JasonSean.Asariah@calbaptist.edu) | [linkedin.com/in/JasonAsariah](https://www.linkedin.com/in/JasonAsariah)

## EDUCATION

### California Baptist University, Riverside, CA

*Bachelor of Science in Electrical and Computer Engineering (ABET Accredited) - GPA 4.0*

**Expected: April 2027**

*Minor in Computer Science*

*President's List*

**Fall 2023 – Present**

## TECHNICAL SKILLS

**Programming Languages:** Python, Java, C++/C, Arduino C

**Engineering Design and Developer Tools:** VS Code, PyCharm, IntelliJ, Arduino IDE, PlatformIO, GitHub, Fusion 360 Modeling/Electronics, Cura, Easy EDA, MATLAB, Excel, AutoCAD, Jira, Altium, LabVIEW, Linux, TortoiseSVN, Xpediton Designer, Xpediton Layout

**Equipment:** Soldering Iron, Drill Press, Solder Reflow Oven, 3D Printers, Oscilloscope, Digital Multimeter (DMM), NI DAQs, Power Supply, Function Generator, Differential Probes

## ELECTRICAL ENGINEERING EXPERIENCE

### SpaceX, Hawthorne, CA

**May 2026 – September 2026**

*Electrical Engineering Intern* | Xpediton Designer, Xpediton Layout, LTspice, Excel, DMM, Oscilloscope, Differential Probes

- Owned design, development, and validation for four satellite flight prototype PCBs
- Designed four PCB schematics with high-speed parallel LVDS, SPI, differential I<sup>2</sup>C, flash memory, precision voltage/current references, and power sequencing.
- Led end-to-end board development collaborating with layout, supply chain, manufacturers, and vendors.
- Partnered with thermal and mechanical teams on thermal dissipation requirements, component placement, connector selection, high-speed harness selection and board sizing.
- Designed schematic and layout of two test coupon PCBs with high-speed signals to validate the prototype flight boards
- Validated board functionality, including power, high-speed interfaces, interconnects, and digital communications.
- Wrote low-speed software for board validation and collaborated with the FPGA team on high-speed signal validation test plans

### SpaceX, Hawthorne, CA

**May 2025 – August 2025**

*Electrical Engineering Intern* | Altium, NX, Excel, DMM, Oscilloscope, NI DAQs, Jira, TortoiseSVN

- Rapid design of flight harnesses for Dragon capsule for various sensors and heaters in constrained locations while coordinating with integration, structures, thermal, supply chain, materials, and harness/heater manufacturing teams for an end-to-end solution
- Developed power analysis tool to analyze load balancing across Dragon avionics system
- Drove qualification campaign for first time flown sensor and harness, ensuring flight readiness of design
- Designed schematic for interface PCB (IsoSPI, SPI, USB) to collect data and simulate environments for new flight hardware

### Bourns Inc., Riverside, CA

**May 2024 – May 2025**

*Engineering Intern* | EasyEDA, Drill Press, Solder Reflow Oven, Excel, DMM

- Enhanced thermal protection product's accuracy by 20% by identifying design flaws and redesigning the device
- Designed PCBs and manufactured test housings for overvoltage protection devices, enabling small-scale thermal testing to validate product performance under high temperature conditions

## Personal Project

*Quadrupedal Robotics Research* | Arduino IDE, PlatformIO, VS Code, Fusion 360, 3D Printing, DMM

**May 2020 – May 2024**

- Designed second iteration of quadrupedal robot prototype that has dynamic balancing
- Designed both electronic and mechanical systems, optimized programming with object-oriented approaches

## LEADERSHIP EXPERIENCE

### California Baptist University Robotics Team, Riverside, CA

**September 2023 - Present**

**President** | Summer 2026–Present | **Vice President** | Spring 2024–Spring 2026 | **Senior Electronics Lead** | Fall 2023–Spring 2026

- Lead a 30-member VEX U robotics team, overseeing technical development, project schedules, competition readiness, and coordination across mechanical, electrical, software, and documentation subteams.
- Previously led an 8–12-member electronics subteam in developing a PCB for sensor data acquisition, control, and communication systems using RS-485, I<sup>2</sup>C, UART, and USB.
- Develop and troubleshoot software/firmware for microcontrollers and Linux systems using debugging techniques and troubleshoot hardware using various circuit analysis tools
- Helped the team qualify for the VEX Robotics World Championship for three consecutive seasons: 2023–24, 2024–25, and 2025–26.